State-of-the-art technologies

- Semiconductor processing (SiO2, Si3N4, etc)
- Electroplating / electroless deposition (Ni, NiMn, NiFe, AuCo, PdNi, AuNi, Au, Ag, Pt, Cu, Ir, Sn, SnCu, SnBi, SnPb, In)
- Sputtering (Au, Cu, Cr, Pt, Al, Ti, TiW, pPt, TiN)
- Wet etching and dry etching
- Photolithography and polymer processing (Polyimide, BCB, SU8, AZ, dry resist, …)
- Bonding & Packaging
- Analysis and characterization (profile, FIB, TEM, Auger spectroscopy, EDX, X-ray diffraction, etc.)
- Rapid Thermal Processing (silicidation, oxidation, annealing)
- Rapid prototyping & stereolithographic forming
- LASER cutting/drilling
- Fine line screen printing
- Mechanical property testing (indentation, tensile test, etc.)
- Injection moulding and tool manufacturing
- CAD & machine shop services

For

- Volumes ranging from R&D, prototyping to mass production
- Substrates: Semiconductor 4”, 6”, 8”; Solar 125mm x 125mm, 156mm x 156mm
- Applications: solar industry, Microsystems & semiconductors, medical devices